

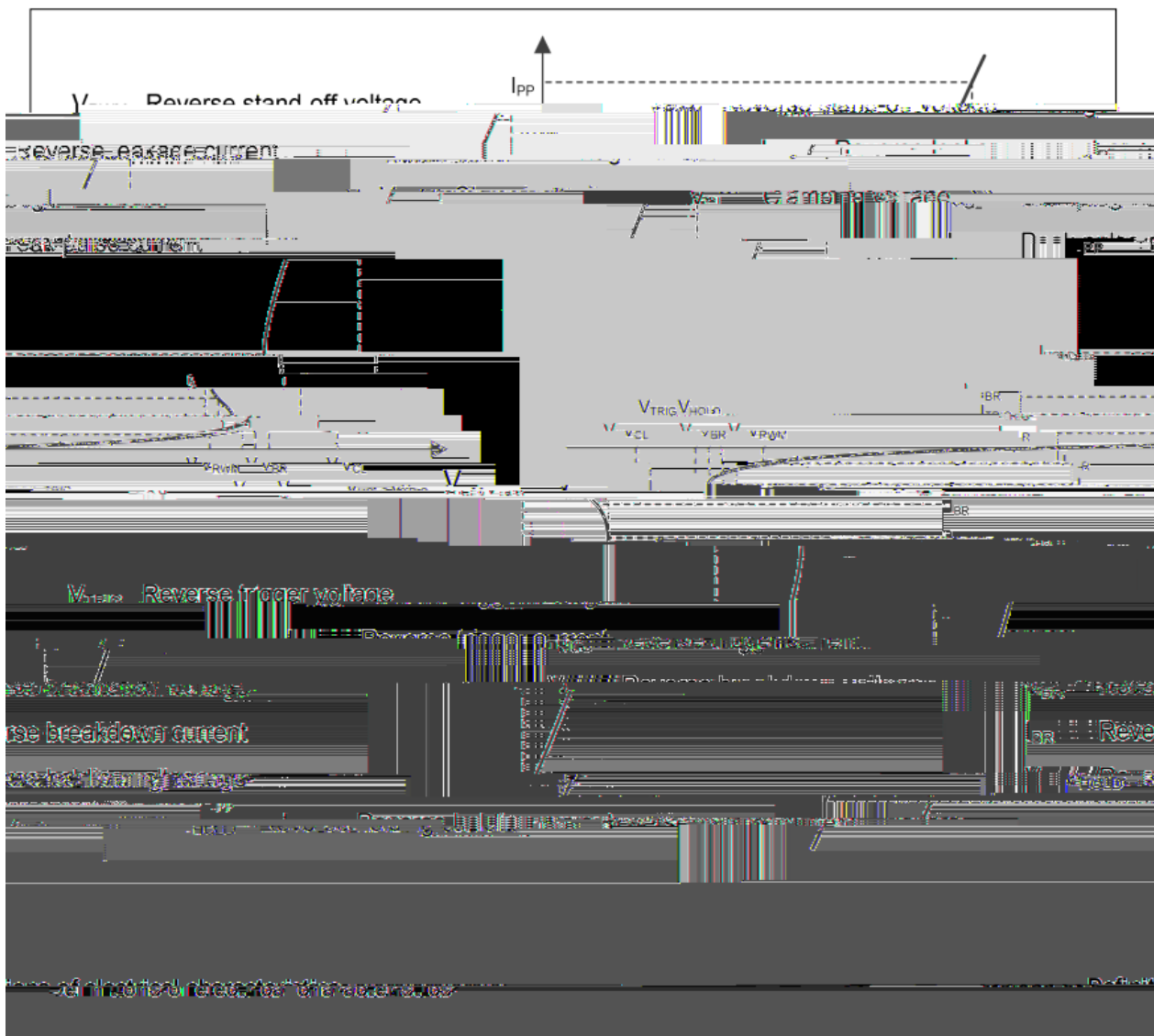
Parameter	Symbol	Rating	Unit
Peak pulse power ($t_p = 8/20 \text{ s}$)	P_K	420	W
Peak pulse current ($t_p = 8/20 \text{ s}$)	I_{PP}	7	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	± 30	KV
ESD according to IEC61000-4-2 contact discharge		± 30	
Junction temperature	T_J	125	$^{\circ}\text{C}$
Storage temperature	T_{STG}	-55~+150	

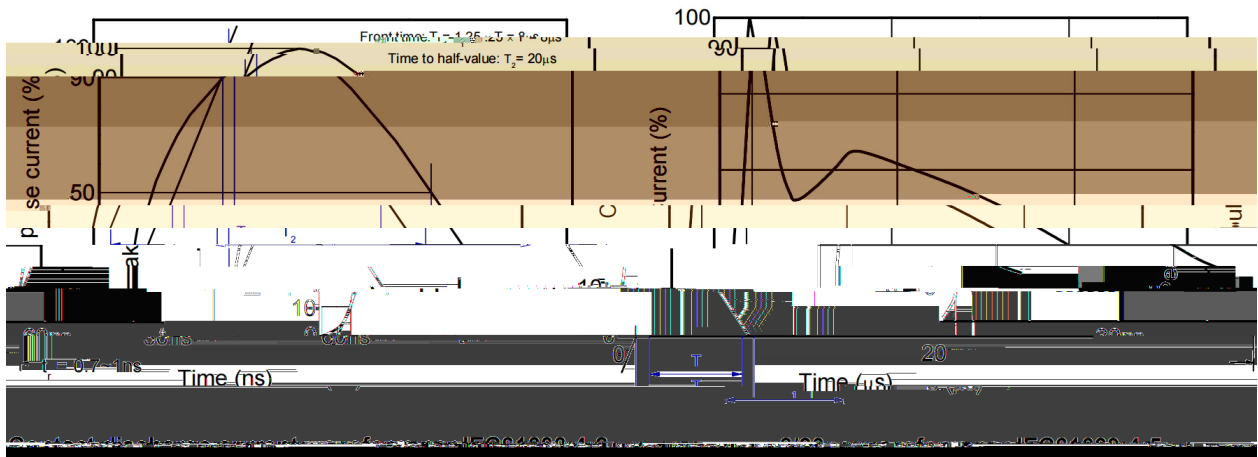
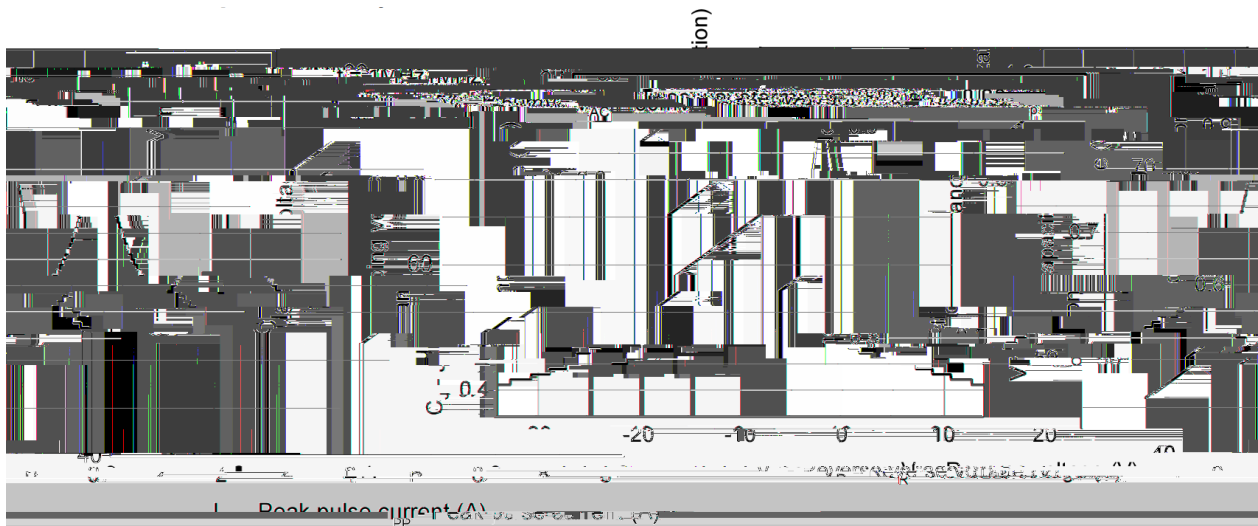
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse maximum working voltage	V_{RWM}				≈ 36	V
Reverse leakage current	I_R	$V_{RWM} = \approx 36\text{V}$			100	nA
Reverse breakdown voltage ¹⁾	V_{BR}	$I_T = 1\text{mA}$	36			V
Clamping voltage ²⁾	V_C	$I_{PP} = 1\text{A } t_p = 8/20 \text{ s}$		46	48	V
		$I_{PP} = 7\text{A } t_p = 8/20 \text{ s}$		75	77	V
		$V_{ESD}=8\text{KV}^{3)}$		65		V
Junction capacitance	C_J	$V_R = 0\text{V } f = 1\text{MHz}$		15	20	pF
Clamping voltage ⁴⁾	V_{CL}	$I_{PP} = 16\text{A } t_p = 100\text{ns}$		60		V
Dynamic resistance ⁴⁾	R_{DYN}			0.22		

Notes:

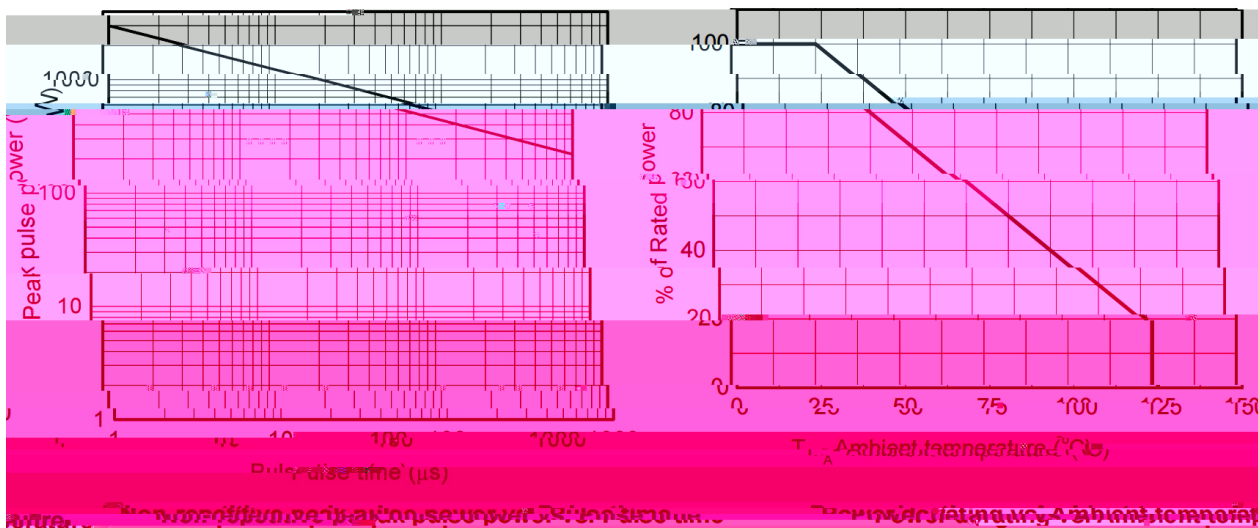
- 1) V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C .
- 2) Non-repetitive current pulse, according to IEC61000-4-5.
- 3) Contact discharge mode, according to IEC61000-4-2.
- 4) TLP parameter: $Z_0 = 50 \Omega$, $t_p = 100\text{ns}$, $t_r = 2\text{ns}$, averaging window from 60ns to 80ns. R_{DYN} is calculated from 4A to 16A.

Rev.A Mar.-2024



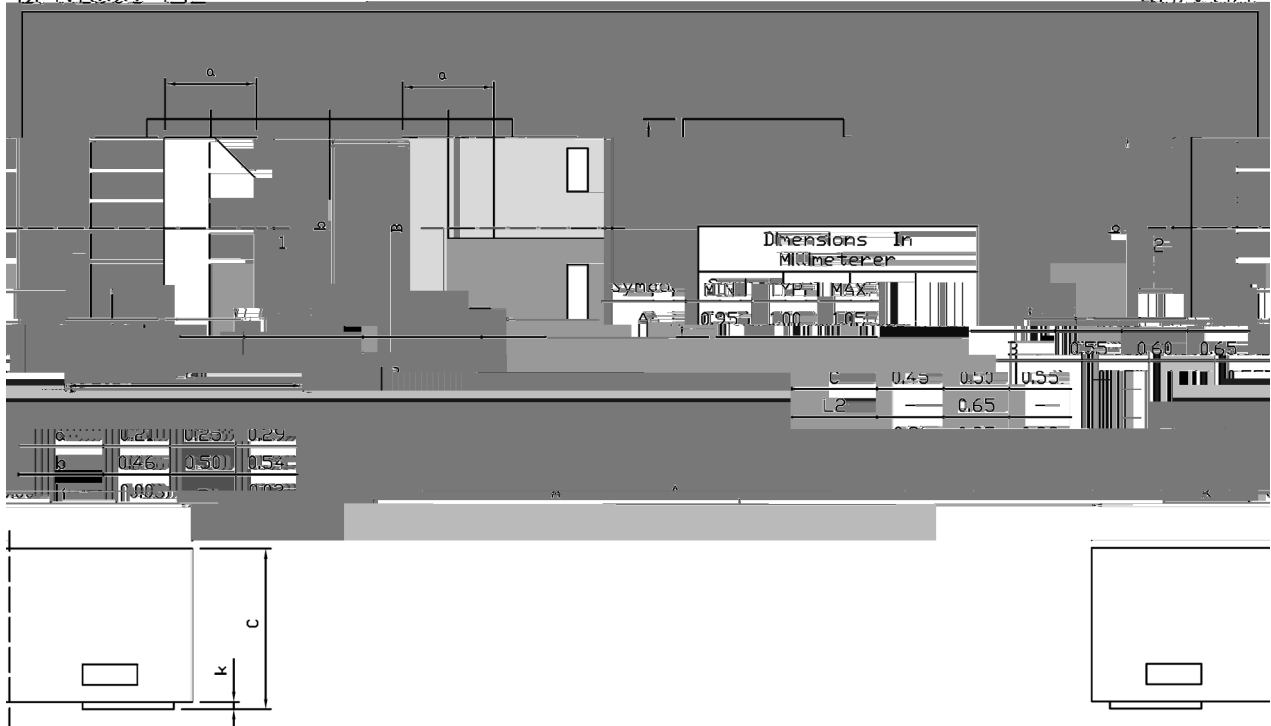


Reverse voltage Clamping voltage vs. Peak pulse current Capacitance vs. Reverse voltage



DFN1006-2L

Unit:mm



Rev.01 202108



Temperature Profile for IR Reflow Soldering(Pb-Free)

- 1

150 180

60 90sec;
- 2

245±5

5±0.5sec;
- 3

2 10 /sec.
- Note:

1.Preheating:150~180 , Time:60~90sec.

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

260±5

10±1 sec.

Temp.:260±5

Time:10±1 sec

/ REEL

Package Type	Units	Dimension	(unit mm ³)	Area (mm ²)	Volume (mm ³)	Weight (g)
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